



## Features

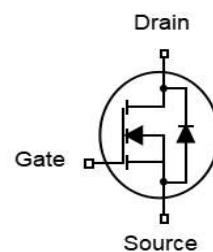
- N-Channel
- Lead free product is acquired
- High Power and current handing capability
- 100% EAS Tested

$V_{DS}$	40	V
$R_{DS(on),TYP}$ @ $V_{GS}=10\text{ V}$	2.2	$\text{m}\Omega$
$R_{DS(on),TYP}$ @ $V_{GS}=4.5\text{ V}$	3.3	$\text{m}\Omega$
$I_D$	120	A

DFN5x6



Part ID	Package Type	Marking	Packing
ZT022N04G	DFN5x6	ZT022N04G	5000pcs/Reel



## Absolute Maximum Ratings

Symbol	Parameter	Rating	Unit	
<b>Common Ratings (T<sub>c</sub>=25°C Unless Otherwise Noted)</b>				
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V	
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	40	V	
$T_J$	Maximum Junction Temperature	150	°C	
$T_{STG}$	Storage Temperature Range	-55 to 150	°C	
$I_{DM}$	Drain Current-Continuous@ Current-Pulsed (Note 1)	$T_c=25^\circ\text{C}$	444	A
<b>Mounted on Large Heat Sink</b>				
$I_D$	Drain Current-Continuous	$T_c=25^\circ\text{C}$	120	A
		$T_c=100^\circ\text{C}$	70	A
$P_D$	Maximum Power Dissipation	$T_c=25^\circ\text{C}$	58	W
		$T_c=100^\circ\text{C}$	23	W
$R_{\theta JC}$	Thermal Resistance-Junction to Case	2.15	°C/W	
<b>Drain-Source Avalanche Ratings</b>				
EAS	Avalanche Energy, Single Pulsed (Note 2)	576	mJ	



**Electrical Characteristics ( $T_j=25^\circ\text{C}$  unless otherwise noted)**

Symbol	Parameter	Condition	Min	Typ	Max	Unit
<b>Static Electrical Characteristics @ <math>T_j=25^\circ\text{C}</math> (unless otherwise stated)</b>						
V(BR)DSS	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}, I_D=250\mu\text{A}$	40	--	--	V
Idss	Zero Gate Voltage Drain Current	$V_{DS}=40\text{V}, V_{GS}=0\text{V}$	--	--	1	$\mu\text{A}$
IGSS	Gate-Body Leakage Current	$V_{GS}=\pm 20\text{V}, V_{DS}=0\text{V}$	--	--	$\pm 100$	nA
VGS(th)	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	1.0	1.7	2.5	V
RDS(on)	Drain-Source On-State Resistance	$V_{GS}=10\text{V}, I_D=20\text{A}$	--	2.2	2.7	$\text{m}\Omega$
RDS(on)	Drain-Source On-State Resistance	$V_{GS}=4.5\text{V}, I_D=20\text{A}$	--	3.3	4.2	$\text{m}\Omega$
gFS	Forward Transconductance	$V_{DS}=5\text{V}, I_D=20\text{A}$	--	38	--	S
<b>Dynamic Electrical Characteristics @ <math>T_j = 25^\circ\text{C}</math> (unless otherwise stated)</b>						
Ciss	Input Capacitance	$V_{DS}=20\text{V}, V_{GS}=0\text{V}, f=1\text{MHz}$	--	6460	--	pF
Coss	Output Capacitance		--	455	--	pF
Crss	Reverse Transfer Capacitance		--	276	--	pF
Rg	Gate Resistance	f=1MHz	--	0.67	--	$\Omega$
Qg	Total Gate Charge	$V_{DS}=20\text{V}, I_D=20\text{A}, V_{GS}=10\text{V}$	--	112	--	nC
Qgs	Gate-Source Charge		--	16.7	--	nC
Qgd	Gate-Drain Charge		--	26.5	--	nC
<b>Switching Characteristics</b>						
Td(on)	Turn-on Delay Time	$V_{DS}=20\text{V}, R_L=1\Omega, R_G=3\Omega, V_{GS}=10\text{V}$	--	18	--	ns
Tr	Turn-on Rise Time		--	4.4	--	ns
Td(off)	Turn-Off Delay Time		--	67	--	ns
Tf	Turn-Off Fall Time		--	9.5	--	ns
<b>Source-Drain Diode Characteristics@ <math>T_j = 25^\circ\text{C}</math> (unless otherwise stated)</b>						
ISD	Source-Drain Current (Body Diode)		--	--	120	A
VSD	Forward on voltage <sup>(Note 3)</sup>	$I_S = 20\text{A}, V_{GS}=0\text{V}$	--	--	1.2	V
Trr	Reverse Recovery Time	$T_j=25^\circ\text{C}, I_F=20\text{A}, V_{GS}=0\text{V}, \frac{di}{dt}=500\text{A}/\mu\text{s}$	--	6	--	ns
Qrr	Reverse Recovery Charge		--	14	--	nC

Notes :

1.Repetitive Rating: Pulse width limited by maximum junction temperature.

2.E<sub>AS</sub> condition:  $T_j=25^\circ\text{C}, V_{DD}=40\text{V}, V_G=10\text{V}, R_g=25\Omega, L=0.5\text{mH}$ .

3.Repetitive Rating: Pulse width limited by maximum junction temperature.



## Typical Electrical And Thermal Characteristics (Curves)

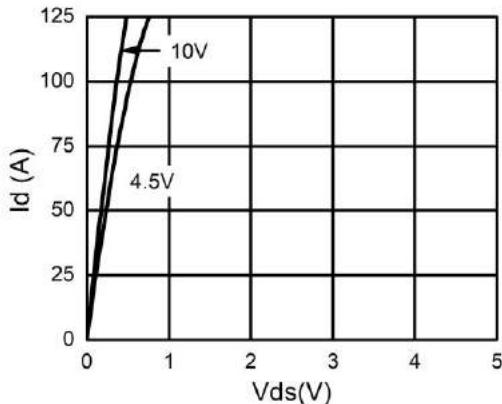


Figure 1. Output Characteristics

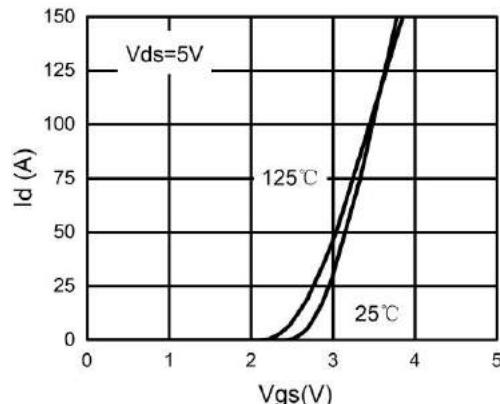


Figure 4. Transfer Characteristics

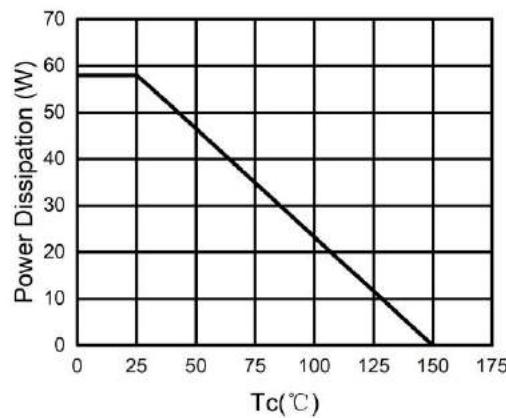


Figure 2. Power Dissipation

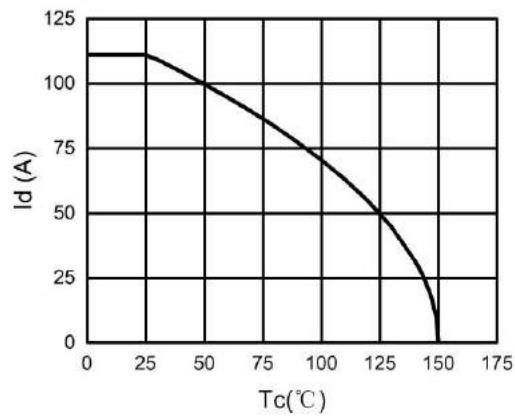


Figure 5. Drain Current

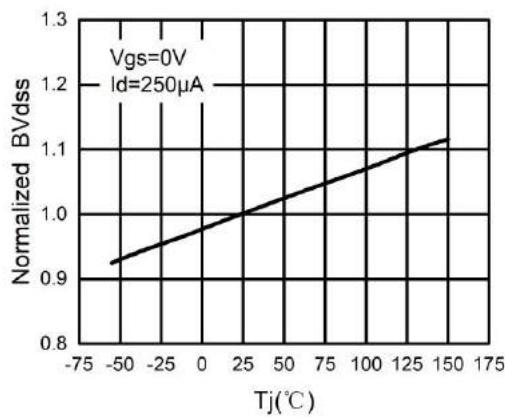


Figure 3.  $\text{BV}_{dss}$  vs Junction Temperature

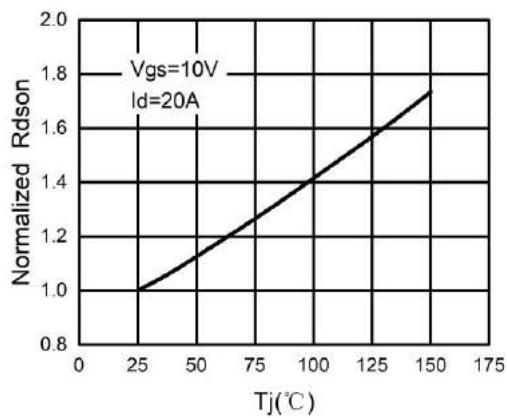


Figure 6.  $R_{DS(ON)}$  vs Junction Temperature

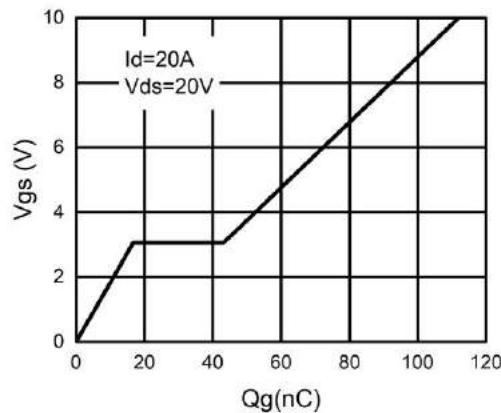


Figure 7. Gate Charge Waveforms

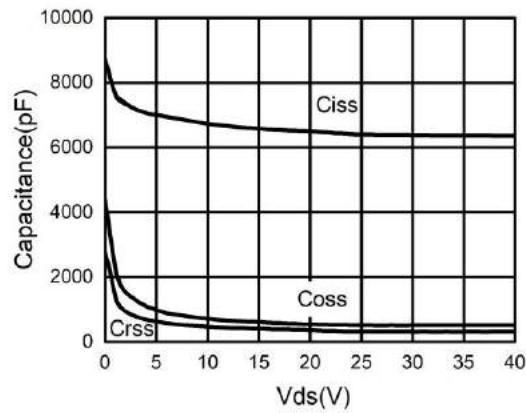


Figure 9. Capacitance

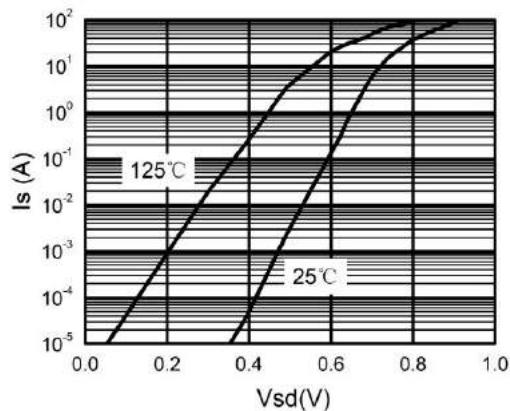


Figure 8. Body-Diode Characteristics

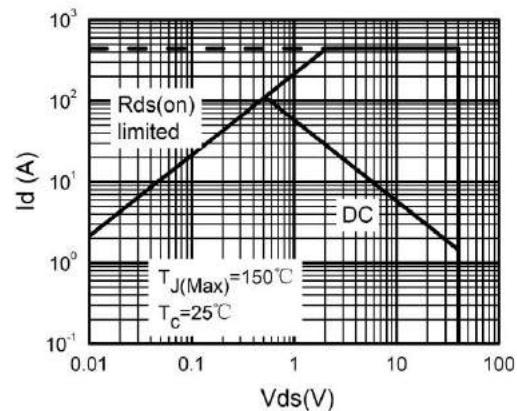
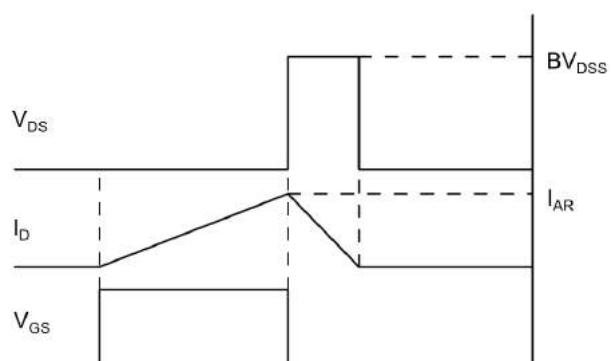
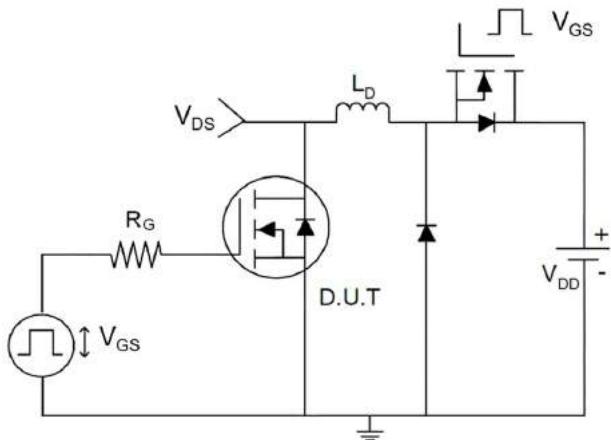


Figure 10. Maximum Safe Operating Area

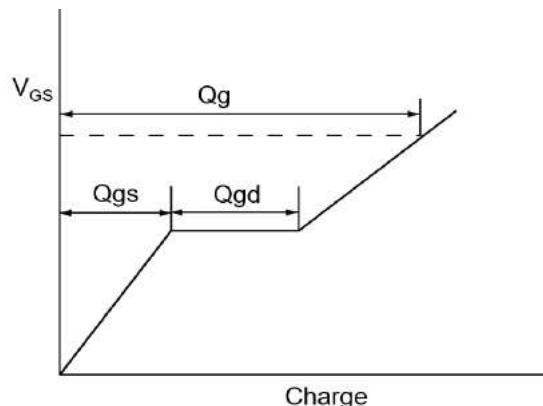
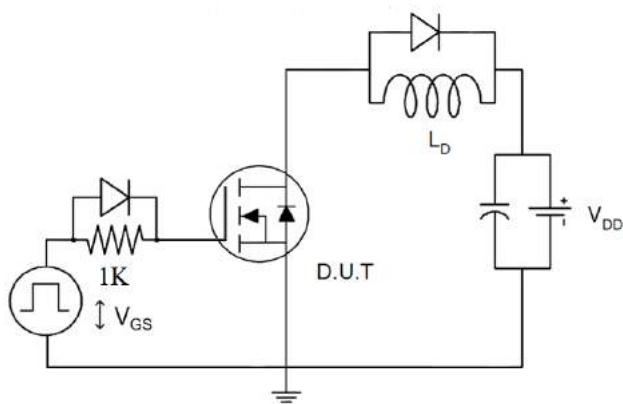


## Test Circuit

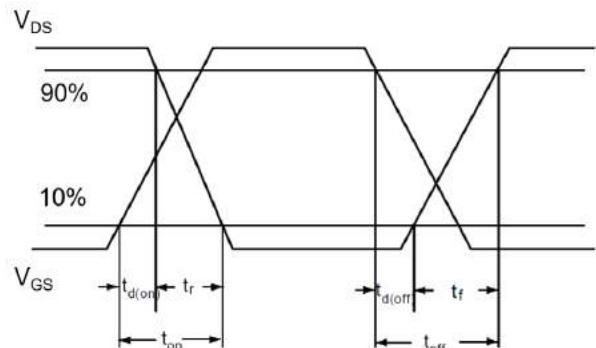
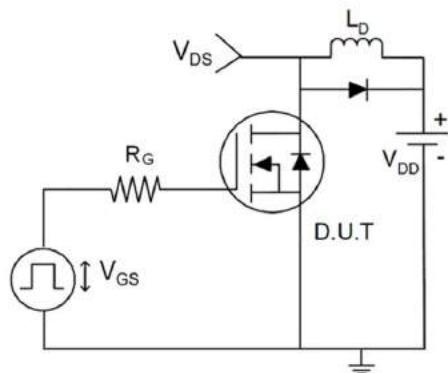
### 1) $E_{AS}$ Test Circuits



### 2) Gate Charge Test Circuit

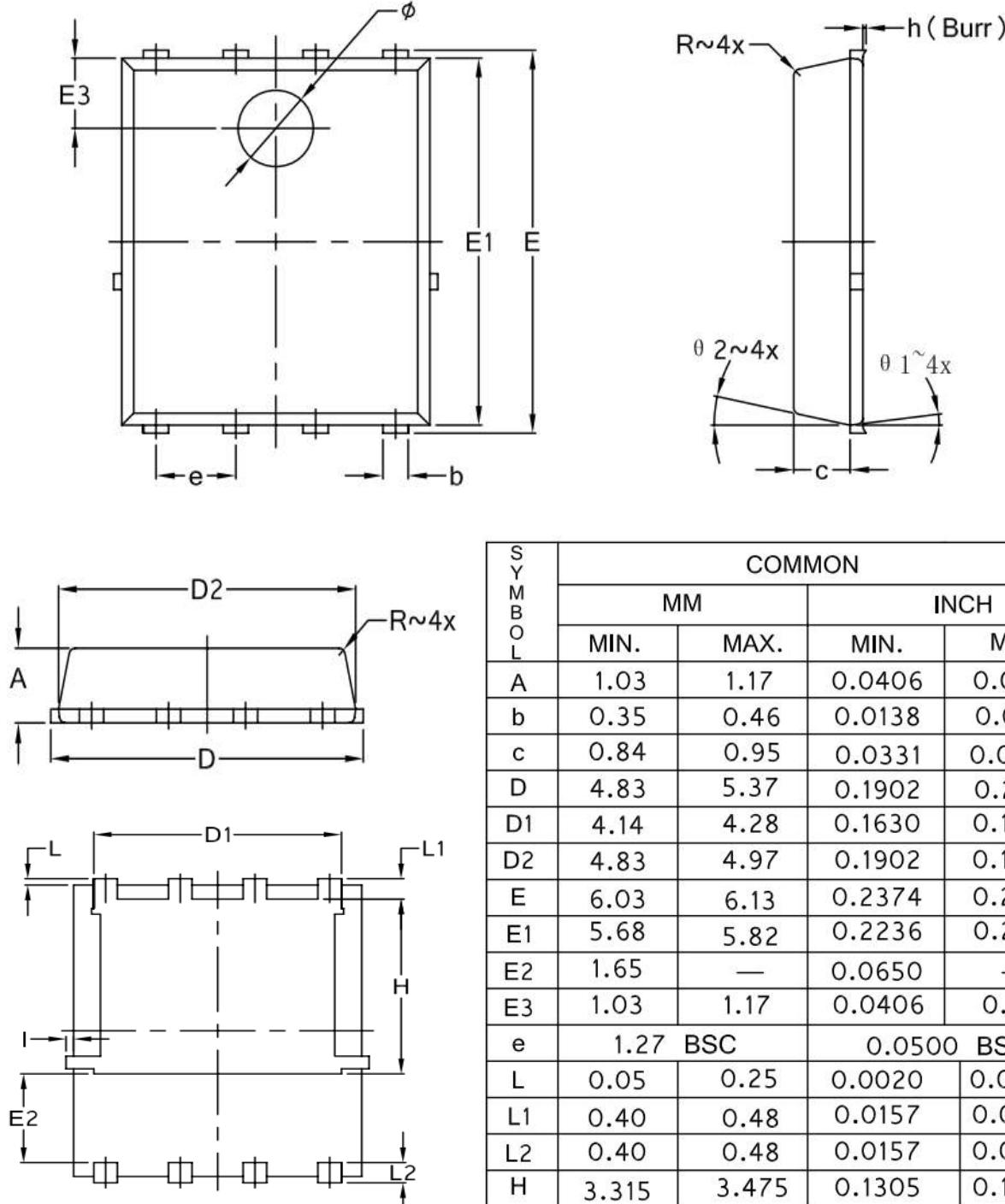


### 3) Switch Time Test Circuit





## DFN5x6-8L Package Information



SYMBOL	COMMON			
	MM		INCH	
	MIN.	MAX.	MIN.	MAX.
A	1.03	1.17	0.0406	0.0461
b	0.35	0.46	0.0138	0.0181
c	0.84	0.95	0.0331	0.0374
D	4.83	5.37	0.1902	0.2114
D1	4.14	4.28	0.1630	0.1685
D2	4.83	4.97	0.1902	0.1957
E	6.03	6.13	0.2374	0.2413
E1	5.68	5.82	0.2236	0.2291
E2	1.65	—	0.0650	—
E3	1.03	1.17	0.0406	0.0461
e	1.27 BSC	—	0.0500 BSC	—
L	0.05	0.25	0.0020	0.0098
L1	0.40	0.48	0.0157	0.0189
L2	0.40	0.48	0.0157	0.0189
H	3.315	3.475	0.1305	0.1368
I	—	0.16	—	0.0063
$\phi$	1.13	1.27	0.0445	0.0500
R	0.10	—	0.0039	—
$\theta_1$	7° REF	—	7° REF	—
$\theta_2$	12° REF	—	12° REF	—
h	0.08 MAX	—	0.0031	—

## Customer Service

Sales and Service:

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